

REMARKS

Reconsideration of this application is respectfully requested in view of the foregoing amendment and the following remarks.

Claims 1-4 were pending in this application. In the Office Action dated April 23, 2003, claims 2 and 4 were rejected under 35 U.S.C. § 112, first paragraph, and claims 1-4 were rejected under 35 U.S.C. § 102(b) as being allegedly anticipated by U.S. Patent No. 5,974,662 to Eldridge et al. ("Eldridge").

By this Amendment, claims 1 and 3 are canceled. Claims 2 and 4 are amended, and claims 5-17 have been added. Support for the amendments to the claims and to the new claims can be found in the specification of the present application. For the reasons stated below, Applicant respectfully submits that all claims pending in this application are in condition for allowance.

With regard to the rejection under 35 U.S.C. § 112, first paragraph, the Office Action states that the specification and drawings do not provide support for a wire drawing operation. In response, Applicant respectfully draws Examiner's attention to page 10, lines 7-19 and to page 14, lines 11-21. Each of embodiments 1 - 7, for example, additionally disclose the results of wire drawing operation for the Ni or Ni alloy plated fine wire. Accordingly, Applicant submits that adequate support is demonstrated in the specification, and respectfully requests that this ground of rejection be withdrawn.

In the Amendment, to clarify the claimed subject matter, claim 2 has been amended to now recite that a "nickel plating or nickel alloy plating is applied to the surface of a core material

made of palladium alloy and then a wire drawing operation with a wire drawing die is performed.” Similarly, newly recited claim 10 recites that “nickel plating or nickel alloy plating is applied to the surface of a core material made of beryllium copper alloy and then a wire drawing operation with a wire drawing die is performed.” Support for this amendment can be found, for example, on page 14, lines 11-21 of the specification (“[t]hen, this nickel plated fine wire for the probe was made fine in sequence with a plurality of wire drawing dies to attain the nickel plated fine wire for the probe”).

While Eldridge discloses making a fine wire probe before nickel plating or nickel alloy plating is applied, claims 2 and 10 recite that a fine wire probe is made by a process which (i) a core material made of palladium alloy or beryllium copper alloy is applied with a wire drawing operation, (ii) plating of nickel or nickel alloy is applied *and then* (iii) a wire drawing operation is applied to provide more superior spring characteristic and hardness. Eldridge does not disclose performing a wire drawing operation after nickel plating or nickel alloy plating is applied. Accordingly, Applicant submits that amended claim 2 and newly provided claim 10 are not anticipated by Eldridge.

Claims 4-9 and 11-16 are submitted to also be patentable based at least upon their dependency from patentable independent claims. New independent claim 17 recites that the probe card has a structure where “either cold wire drawn nickel plating or cold wire drawn nickel alloy plating is applied to the surface of a core material made of palladium alloy.” For the same reasons described above, Applicant submits that this claim also is patentable over the cited references.

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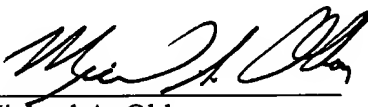
In view of the foregoing all of the claims in this case are believed to be in condition for allowance. Should the Examiner have any questions or determine that any further action is desirable to place this application in even better condition for issue, the Examiner is encouraged to telephone applicant's undersigned representative at the number listed below.

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Respectfully submitted,

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